



## Product Change Notification: DSNO-22WFHG168

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### Date:

26-Oct-2026

### Product Category:

Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Power Management - System Supervisors/Voltage Detectors

### Notification Subject:

CCB 8448 Initial Notice: Qualification of G630AY as an additional mold compound for selected TC1270A, TC1271A, TC1270AN, MCP6291R, MCP6L91R, MCP6271R, MCP6L71R, MCP6281R, MCP6001, MCP6L01, MCP6G01R, MCP6021R, MCP6271, MCP6281, MCP6291, MCP6L71, MCP6143, MCP6043, MCP6541, MCP6546, MCP603, MCP601, MCP6L1R, MCP6273, MCP6283, MCP6293, MCP6241R, MCP6541R, MCP6546R, MCP6L01R, MCP6401R, MCP111 and MCP6231R device families available in 5L and 6L SOT-23 (1.6mm) packages at MMT assembly site.

### Affected CPNs:

[DSNO-22WFHG168\\_Affected\\_CPN\\_10262026.pdf](#)

[DSNO-22WFHG168\\_Affected\\_CPN\\_10262026.csv](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of G630AY as an additional mold compound for selected TC1270A, TC1271A, TC1270AN, MCP6291R, MCP6L91R, MCP6271R, MCP6L71R, MCP6281R, MCP6001, MCP6L01, MCP6G01R, MCP6021R, MCP6271, MCP6281, MCP6291, MCP6L71, MCP6143, MCP6043, MCP6541, MCP6546, MCP603, MCP601, MCP6L1R, MCP6273, MCP6283, MCP6293, MCP6241R, MCP6541R, MCP6546R, MCP6L01R, MCP6401R, MCP111 and MCP6231R device families available in 5L and 6L SOT-23 (1.6mm) packages at MMT assembly site.

**Pre and Post Summary Changes:**

|                             |                      | Pre Change                                                   |                       | Post Change                                        |                       | Change<br>(Yes/No) |
|-----------------------------|----------------------|--------------------------------------------------------------|-----------------------|----------------------------------------------------|-----------------------|--------------------|
| Assembly Site               |                      | Microchip Technology<br>Thailand (Branch)<br>(MMT)           |                       | Microchip Technology<br>Thailand (Branch)<br>(MMT) |                       | No                 |
| Wire Material               |                      | CuPdAu                                                       |                       | CuPdAu                                             |                       | No                 |
| Die Attach Material         |                      | 84-3J<br>(PFAS-free)                                         | 8006NS<br>(PFAS-free) | 84-3J<br>(PFAS-free)                               | 8006NS<br>(PFAS-free) | No                 |
| Molding Compound Material   |                      | G600V                                                        |                       | G600V                                              | G630AY                | Yes                |
| Lead-Frame Material         |                      | CDA194                                                       |                       | CDA194                                             |                       | No                 |
| Lead-Frame Paddle Size      | 5L SOT-23<br>(1.6mm) | 66 x 48 mils                                                 |                       | 66 x 48 mils                                       |                       | No                 |
|                             | 6L SOT-23<br>(1.6mm) | 72 x 41 mils                                                 |                       | 72 x 41 mils                                       |                       | No                 |
| Lead-Frame DAP Surface Prep |                      | Ag-RT                                                        |                       | Ag                                                 |                       | Yes                |
| Lead-Frame Design           |                      | See 'Pre and Post Change Summary' attachment for comparison. |                       |                                                    |                       | Yes                |

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability by qualifying G630AY as additional molding compound material at MMT assembly site.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** December 2026

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

|                          | October 2026 |    |    |    |    | > | December 2026 |    |    |    |
|--------------------------|--------------|----|----|----|----|---|---------------|----|----|----|
| Work Week                | 40           | 41 | 42 | 43 | 44 |   | 49            | 50 | 51 | 52 |
| Initial PCN Issue Date   |              |    |    |    | x  |   |               |    |    |    |
| Qual Report Availability |              |    |    |    |    |   | x             |    |    |    |
| Final PCN Issue Date     |              |    |    |    |    |   | x             |    |    |    |

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** October 26, 2026: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**[PCN\\_DSNO-22WFHG168\\_Qual\\_Plan.pdf](#)**

**[PCN\\_DSNO-22WFHG168\\_Pre and\\_Post\\_Change Summary.pdf](#)**

Please contact your local **[Microchip sales office](#)** with questions or concerns regarding this notification.

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